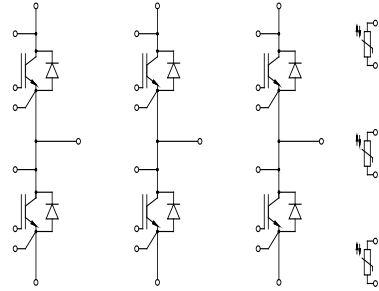
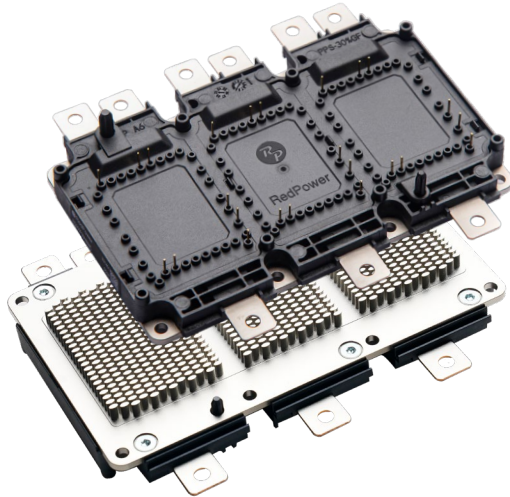


A6 package: 750V 950A IGBT module



等效电路图  
Equivalent Circuit Schematic

**Features:**

- 750V 950A,  $V_{CE(sat)} = 1.43V@25^{\circ}C$
- Direct cooled PinFin Base Plate
- Micro pattern trench/FS Technology
- Low switching losses

**产品特性:**

- 750V 950A,  $V_{CE(sat)} = 1.43V@25^{\circ}C$
- PinFin 直接液冷散热底板
- 微沟槽栅/场终止技术
- 低开关损耗

**Typical Applications:**

- Electric Vehicles
- Motor Drives

**典型应用:**

- 电动汽车
- 电机驱动

## IGBT, Inverter / IGBT, 逆变部分

### Maximum Rated Values / 最大标称参数

Collector-emitter voltage 集电极-发射极电压	$T_{vj}=25^{\circ}\text{C}$	$V_{CES}$	750	V
Implemented collector current 连续集电极电流		$I_{C\text{ nom}}$	950	A
Continuous DC collector current 集电极连续直流电流	$T_F=95^{\circ}\text{C}, T_{vj\text{ max}}=175^{\circ}\text{C}$	$I_C$	570 <sup>1)</sup>	A
Repetitive peak collector current 集电极可重复峰值电流	$t_p=1\text{ms}$	$I_{CRM}$	1900 <sup>1)</sup>	A
Gate-emitter peak voltage 门极-发射极峰值电压		$V_{GES}$	$\pm 20$	V

### Characteristic Values / 性能参数

				min.	typ.	max.	
Collector-emitter saturation voltage 集电极-发射极饱和压降 <sup>2)</sup>	$I_C=450\text{A}, V_{GE}=15\text{V}$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$V_{CE\text{ sat}}$		1.15 1.17 1.17	1.45	V
	$I_C=950\text{A}, V_{GE}=15\text{V}$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$			1.43 1.65	1.9	
Gate threshold voltage 门极阈值电压	$V_{CE}=V_{GE}, I_C=9.6\text{mA}$ ,	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$V_{GE\text{ th}}$	5.0	6.0 3.8	7.0	V
Internal gate resistor 内置门极电阻		$T_{vj}=25^{\circ}\text{C}$	$R_{G\text{ int}}$		0.89		$\Omega$
Input capacitance 输入电容	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=100\text{kHz}, T_{vj}=25^{\circ}\text{C}$		$C_{ies}$		106		nF
Reverse transfer capacitance 反向传输电容	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=100\text{kHz}, T_{vj}=25^{\circ}\text{C}$		$C_{res}$		0.37		nF
Gate charge 门极电荷	$V_{GE}=-8\text{V}\sim+15\text{V}, V_{CE}=400\text{V}$		$Q_G$		4.38		$\mu\text{C}$
Collector-emitter cutoff current 集电极-发射极关断漏电流	$V_{CE}=750\text{V}, V_{GE}=0\text{V}$ ,	$T_{vj}=25^{\circ}\text{C}$	$I_{CES}$			1	mA
Gate-emitter leakage current 门极-发射极漏电流	$V_{CE}=0\text{V}, V_{GE}=20\text{V}$ ,	$T_{vj}=25^{\circ}\text{C}$	$I_{GES}$			400	nA
Turn-on delay time, inductive load 开通延迟时间, 感性负载	$I_C=450\text{A}, V_{CE}=400\text{V}$ $V_{GE}=-8\text{V}/15\text{V}$ $R_{Gon}=1.0\Omega$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$t_{don}$		140 160 162		ns
Rise time, inductive load 上升时间, 感性负载	$I_C=450\text{A}, V_{CE}=400\text{V}$ $V_{GE}=-8\text{V}/15\text{V}$ $R_{Gon}=1.0\Omega$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$t_r$		53 65 67		ns
Turn-off delay time, inductive load 关断延迟时间, 感性负载	$I_C=450\text{A}, V_{CE}=400\text{V}$ $V_{GE}=-8\text{V}/15\text{V}$ $R_{Goff}=5.0\Omega$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$t_{doff}$		756 863 890		ns
Fall time, inductive load 下降时间, 感性负载	$I_C=450\text{A}, V_{CE}=400\text{V}$ $V_{GE}=-8\text{V}/15\text{V}$ $R_{Goff}=5.0\Omega$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$t_f$		77 164 177		ns
Turn-on energy loss per pulse 开通损耗	$I_C=450\text{A}, V_{CE}=400\text{V}, L_s=30\text{nH}$ $V_{GE}=-8\text{V}/15\text{V}, R_{Gon}=1.0\Omega$ $di/dt(T_{vj}=25^{\circ}\text{C})=6750\text{A/us}$ $di/dt(T_{vj}=150^{\circ}\text{C})=5500\text{A/us}$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$E_{on}$		9.65 13.8 15.2		mJ
Turn-off energy loss per pulse 关断损耗	$I_C=450\text{A}, V_{CE}=400\text{V}, L_s=30\text{nH}$ $V_{GE}=-8\text{V}/15\text{V}, R_{Goff}=5.0\Omega$ $dv/dt(T_{vj}=25^{\circ}\text{C})=7600\text{V/us}$ $dv/dt(T_{vj}=150^{\circ}\text{C})=4760\text{V/us}$	$T_{vj}=25^{\circ}\text{C}$ $T_{vj}=150^{\circ}\text{C}$ $T_{vj}=175^{\circ}\text{C}$	$E_{off}$		22.2 31.5 33.6		mJ

<sup>1)</sup> 非测试值, 设计计算所得

<sup>2)</sup> 芯片标称值

SC data 短路耐量	$V_{GE}=15V/-8V$ , $V_{CC}=400V$ , $V_{CEmax} \leq 750V$	$t_p \leq 6\mu s, T_{vj}=25^\circ C$ $t_p \leq 3\mu s, T_{vj}=175^\circ C$	$I_{sc}$		5200 4100		A
Thermal resistance, junction to cooling fluid 结-冷却液热阻	Per IGBT, $\Delta V/\Delta t=10dm^3/min$ $T_F=65^\circ C$		$R_{thJF}$		0.08		K/W
Temperature under switching conditions 工作温度	$t_{op}$ continuous for 10s within a period of 30s, occurrence maximum 3000 times over lifetime		$T_{vj op}$	-40 150		150 175	$^\circ C$

### Diode, Inverter / 二极管, 逆变部分

#### Maximum Rated Values / 最大标称参数

Repetitive peak reverse voltage 可重复反向峰值电压	$T_{vj}=25^\circ C$	$V_{RRM}$	750	V
Implemented forward current 连续正向电流		$I_{F nom}$	950	A
Repetitive peak forward current 可重复正向峰值电流	$t_p=1ms$	$I_{FRM}$	1900 <sup>1)</sup>	A

#### Characteristic Values / 性能参数

			min.	typ.	max.		
Forward voltage 正向通态压降 <sup>2)</sup>	$I_F=450A, V_{GE}=0V$	$T_{vj}=25^\circ C$	$V_F$	1.33	1.75	V	
		$T_{vj}=150^\circ C$		1.21			
		$T_{vj}=175^\circ C$		1.16			
	$I_F=950A, V_{GE}=0V$	$T_{vj}=25^\circ C$		1.59	2.1		
		$T_{vj}=175^\circ C$		1.46			
Peak reverse recovery current 反向恢复峰值电流	$I_F=450A, V_R=400V$ $-di_F/dt=4000A/\mu s(T_{vj}=150^\circ C)$ $V_{GE}=-8V$	$T_{vj}=25^\circ C$ $T_{vj}=150^\circ C$ $T_{vj}=175^\circ C$	$I_{RM}$		343 398 420		A
Recovery charge 反向恢复电荷	$I_F=450A, V_R=400V$ $-di_F/dt=4000A/\mu s(T_{vj}=150^\circ C)$ $V_{GE}=-8V$	$T_{vj}=25^\circ C$ $T_{vj}=150^\circ C$ $T_{vj}=175^\circ C$	$Q_r$		27.5 47.5 55.5		$\mu C$
Reverse recovery energy 反向恢复损耗	$I_F=450A, V_R=400V$ $-di_F/dt=4000A/\mu s(T_{vj}=150^\circ C)$ $V_{GE}=-8V$	$T_{vj}=25^\circ C$ $T_{vj}=150^\circ C$ $T_{vj}=175^\circ C$	$E_{rec}$		7.4 15 17.3		mJ
Thermal resistance, junction to cooling fluid 结-冷却液热阻	Per FRD, $\Delta V/\Delta t=10dm^3/min$ $T_F=65^\circ C$		$R_{thJF}$		0.116		K/W
Temperature under switching conditions 工作温度	$t_{op}$ continuous for 10s within a period of 30s, occurrence maximum 3000 times over lifetime		$T_{vj op}$	-40 150		150 175	$^\circ C$

<sup>1)</sup> 非测试值, 设计计算所得

<sup>2)</sup> 芯片标称值

**NTC-Thermistor/ NTC-热敏电阻**
**Characteristic Values / 性能参数**

		min.	typ.	max.	
Rated resistance 标称电阻	$T_C=25^\circ\text{C}$	$R_{25}$	5.00		K $\Omega$
Deviation of R100 R100 偏移值	$T_C=100^\circ\text{C}$ , $R_{100}=493.3\Omega$	$\Delta R/R$	-5	5	%
Power dissipation 功率耗散	$T_C=25^\circ\text{C}$	$P_{25}$		20	mW
B-value B 值	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$	$B_{25/50}$	3375		K
B-value B 值	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$	$B_{25/80}$	3414		K
B-value B 值	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$	$B_{25/100}$	3436		K

**Module / 模块**

Isolation test voltage 绝缘测试电压	RMS, $f=50\text{Hz}$ , $t=1\text{min}$	$V_{\text{ISOL}}$	3.0		KV
Material of module baseplate 模块底板材料			Cu+Ni <sup>1)</sup>		
Internal isolation 内部绝缘			Si <sub>3</sub> N <sub>4</sub>		
Creepage distance 爬电距离	Terminal to heatsink Terminal to terminal	$d_{\text{Creep}}$	9.0 9.0		mm
Clearance 电气间隙	Terminal to heatsink Terminal to terminal	$d_{\text{Clear}}$	4.5 4.5		mm
Comparative tracking index 相对漏电起痕指数		CTI	200 <sup>2)</sup>		

min. typ. max.

Stray inductance module 模块杂散电感		$L_{\text{sCE}}$	8.5		nH
Module lead resistance, terminals-chip 模块引脚电阻, 端子-芯片	$T_C=25^\circ\text{C}$ , Per switch	$R_{\text{CC}'+\text{EE}'}$	0.75		m $\Omega$
Storage temperature 贮存温度		$T_{\text{stg}}$	-40	125	$^\circ\text{C}$
Mounting torque for module mounting 模块安装力矩	Baseplate to heatsink, Screw M4	M	1.8	2.2	Nm
	Terminal connection, Screw M5		3.6	4.4	
	PCB to frame		0.5	0.6	
Weight 重量		G	760		g

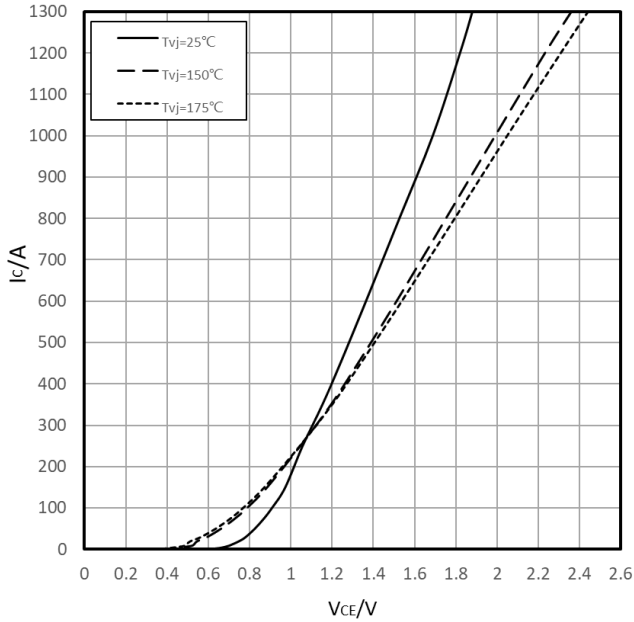
<sup>1)</sup> 铜底板表面镀镍

<sup>2)</sup> CTI 约为 200

**Circuit Diagram / 曲线图**

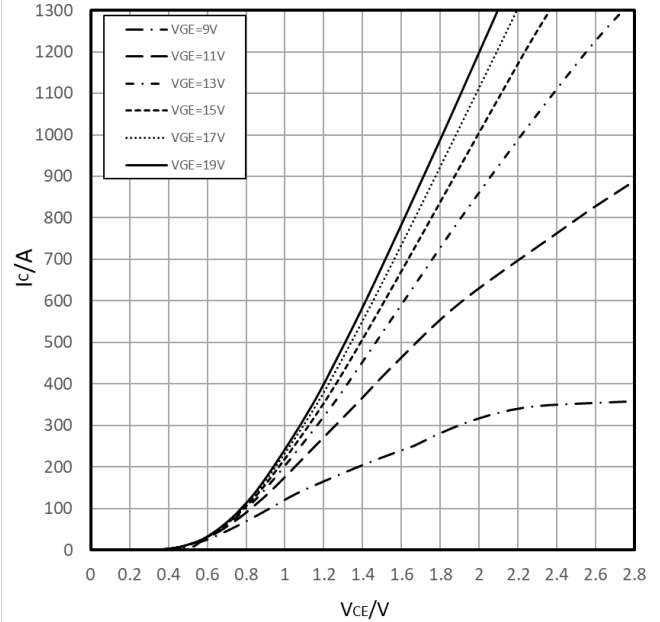
**Output characteristic , Inverter IGBT (typical)**  
**输出特性, 逆变IGBT (典型)**

$I_c=f(V_{CE})$ ,  $V_{GE}=15V$  (Inclusive  $R_{CC'+EE'}$ )



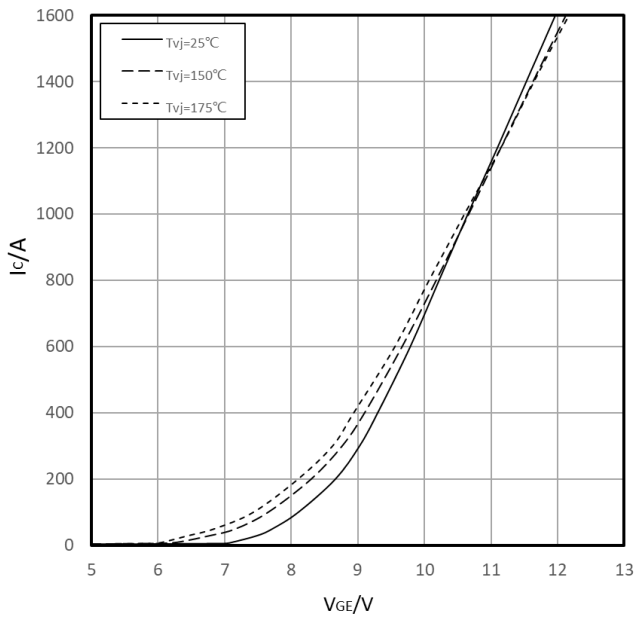
**Output characteristic , Inverter IGBT (typical)**  
**输出特性, 逆变IGBT (典型)**

$I_c=f(V_{CE})$ ,  $T_{vj}=150^\circ C$



**Transfer characteristic , Inverter IGBT (typical)**  
**传输特性, 逆变IGBT (典型)**

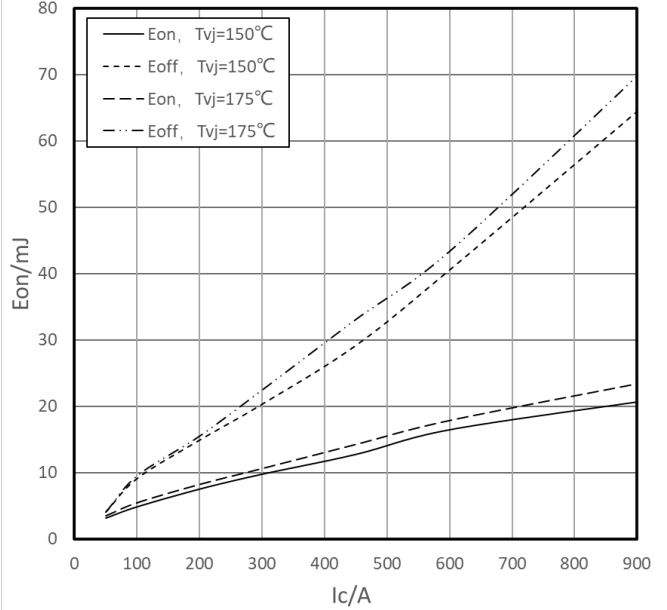
$I_c=f(V_{GE})$ ,  $V_{CE}=20V$



**Switching losses , Inverter IGBT (typical)**  
**开关损耗, 逆变IGBT (典型)**

$E_{on}=f(I_c)$ ,  $E_{off}=f(I_c)$

$V_{GE}=+15V/-8V$ ,  $R_{gon}=1.0\Omega$ ,  $R_{goff}=5.0\Omega$ ,  $V_{CE}=400V$

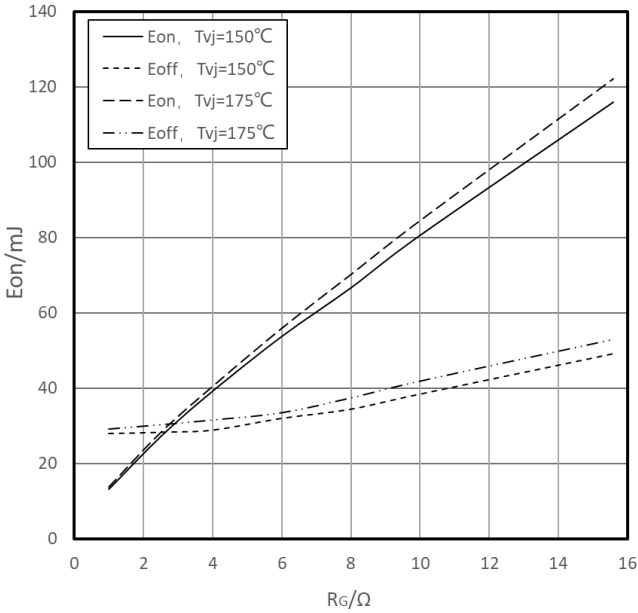


**Switching losses , Inverter IGBT (typical)**

开关损耗, 逆变IGBT (典型)

$E_{on}=f(R_g), E_{off}=f(R_g)$

$V_{GE}=+15V/-8V, I_c=450A, V_{CE}=400V$

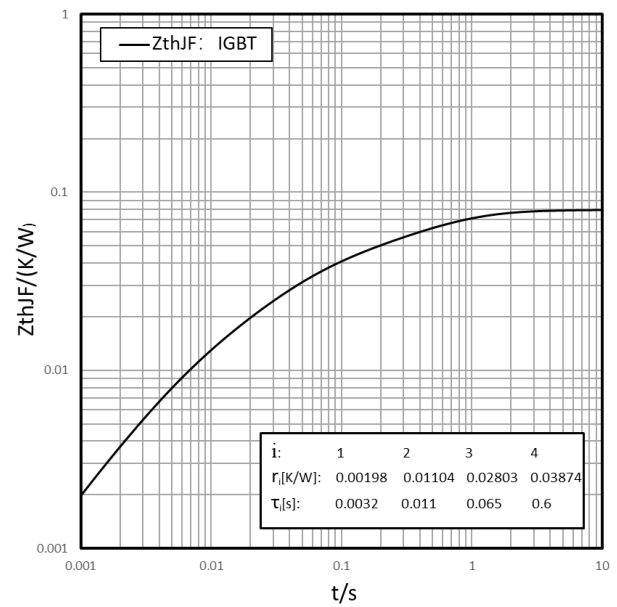


**Transient thermal impedance IGBT, Inverter**

瞬态热阻, 逆变IGBT

$Z_{thJF}=f(t)$

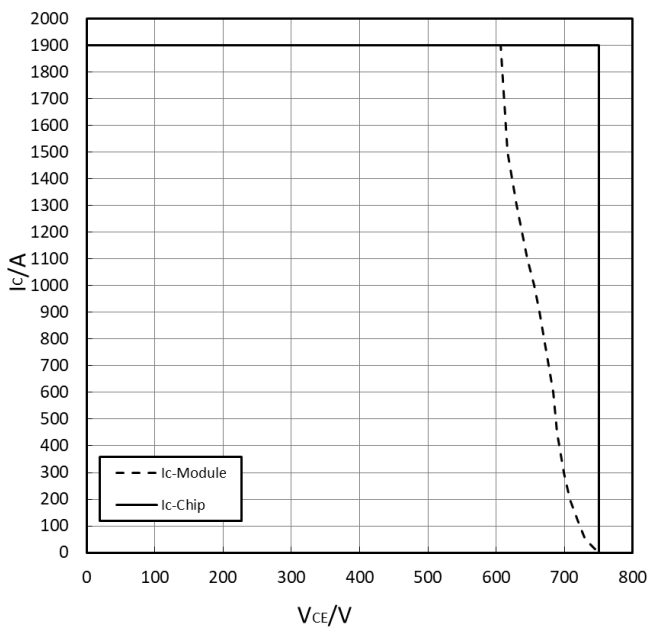
$\Delta V/\Delta t=10dm^3/min; T_f=65^\circ C; 50\% \text{ water}/50\% \text{ ethylenglycol}$



**Reverse bias safe operating area , Inverter IGBT (RBSOA)**

反偏安全工作区, 逆变IGBT (RBSOA)

$I_c=f(V_{CE}), V_{GE}=+15V/-8V, R_{goff}=5.0\Omega, T_{vj}=175^\circ C$

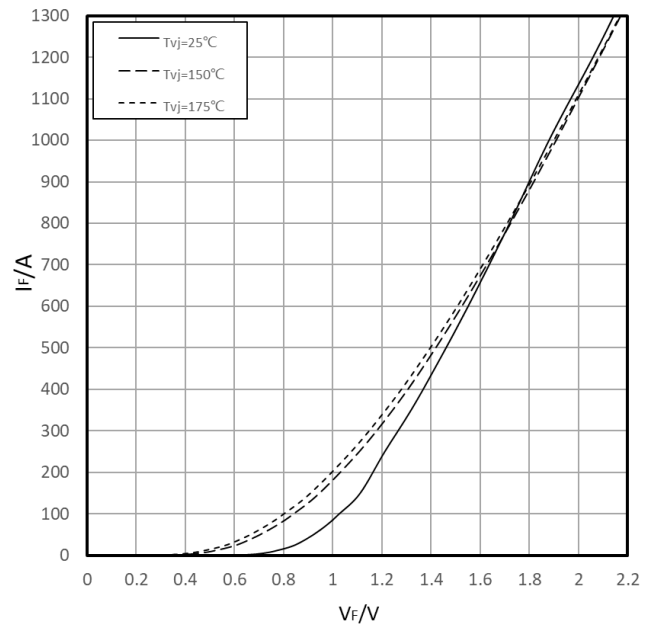


**Forward characteristic , Inverter FRD (typical)**

正向偏压特性, 逆变FRD (典型)

$I_f=f(V_f)$

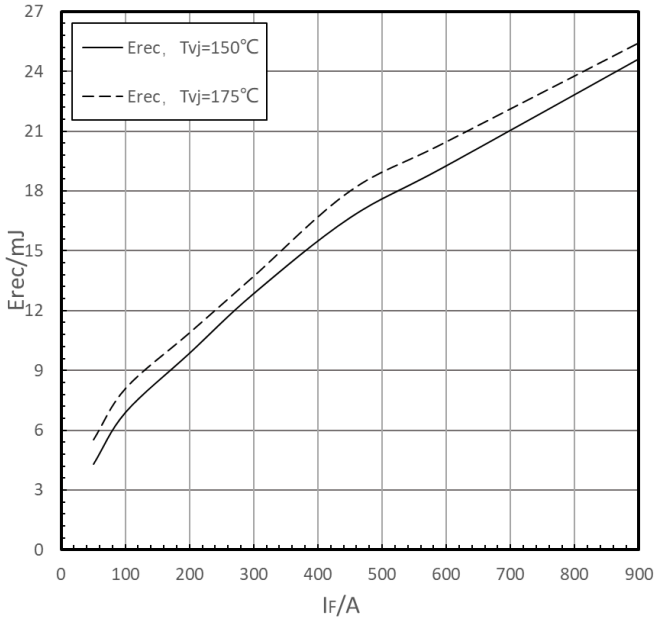
(Inclusive  $R_{CC'+EE'}$ )



**Switching losses , Inverter IGBT (typical)**

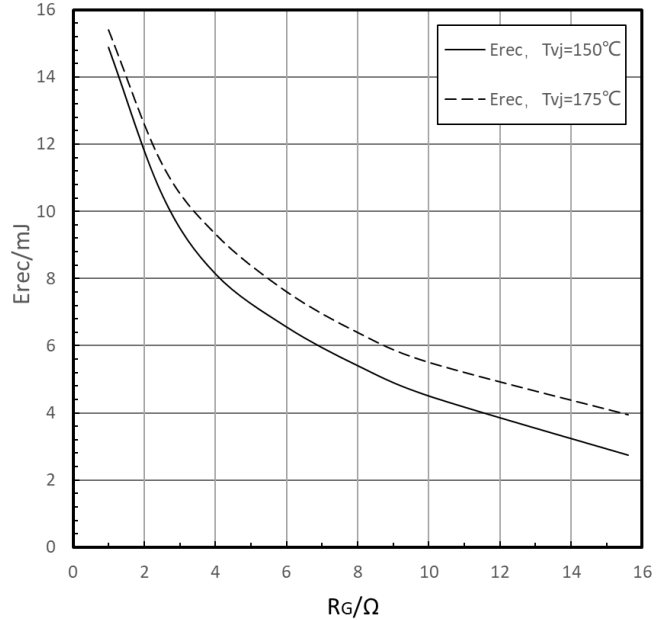
开关损耗, 逆变FRD (典型)

$$E_{rec}=f(I_F), R_{gon}=1.0\Omega, V_{CE}=400V$$


**Switching losses , Inverter FRD (typical)**

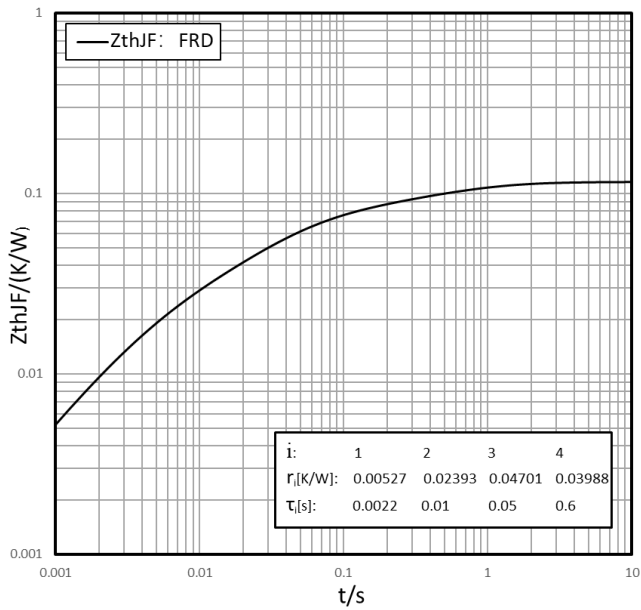
开关损耗, 逆变FRD (典型)

$$E_{rec}=f(R_G), I_F=450A, V_{CE}=400V$$


**Transient thermal impedance FRD, Inverter**

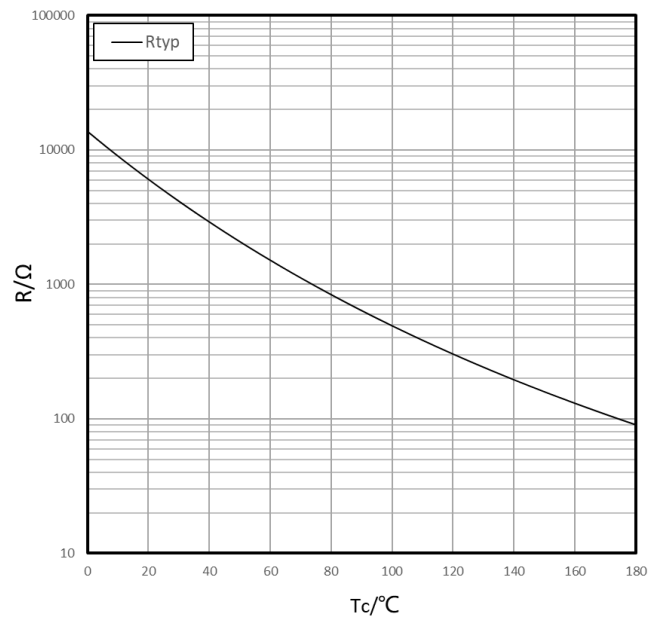
瞬态热阻, 逆变FRD

$$Z_{thJF}=f(t)$$

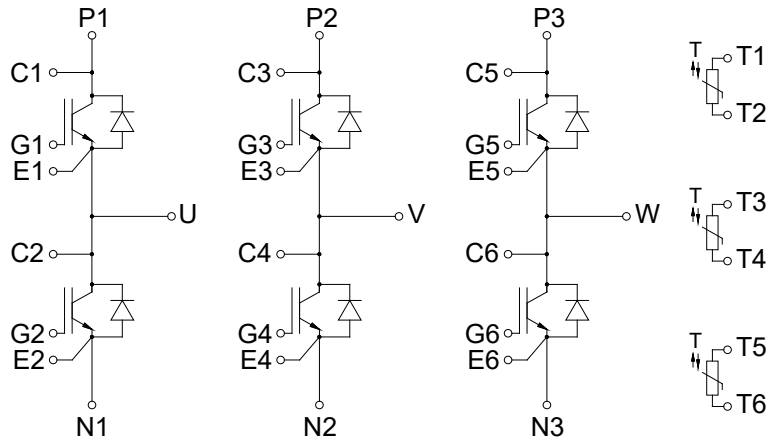
 $\Delta V/\Delta t=10dm^3/min; T_f=65^\circ C; 50\% \text{ water}/50\% \text{ ethylenglycol}$ 

**NTC-Thermistor-temperature characteristic**

负温度系数热敏电阻 温度特性

$$R=f(T)$$



Internal Circuit / 内部电路



Package Dimension / 封装尺寸

Dimensions in Millimeters / 毫米为单位

